

#### Description

The HXY4882S uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

VDS = 40V ID = 8A

 $R_{DS(ON)} < 20m\Omega @ V_{GS}=10 V$ 

### Application

Battery protection

Load switch

Uninterruptible power supply

#### Package Marking and Ordering Information

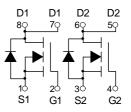
Product ID	Pack	Marking	Qty(PCS)
HXY4882S	SOP-8	4882 XXX YYYY	3000

## Absolute Maximum Ratings@Tj=25°C(unless otherwise specified)

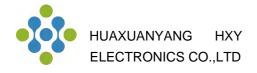
Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	<u>+</u> 20	V
I₀@T₄=25℃	Drain Current, V <sub>GS</sub> @ 4.5V <sup>3</sup>	8	A
I₀@T₄=70℃	Drain Current, V <sub>Gs</sub> @ 4.5V <sup>3</sup>	6	А
Ідм	Pulsed Drain Current <sup>1</sup>	36	А
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation	1.9	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction- ambient <sup>3</sup>	40	°C/W



SOP-8



#### Dual N-Channel MOSFET



#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V	
$\triangle \text{BV}_{\text{DSS}} / \triangle \text{T}$	BVDSS Temperature Coefficient	Reference to $25^{\circ}C$ , I <sub>D</sub> =1mA		0.032		V/°C	
Rds(on)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =7A	16 20		20		
	Static Drain-Source On-Resistance-	V <sub>GS</sub> =4.5V , I <sub>D</sub> =6A		20	26	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage	VGS=VDS . ID =250uA	1.2	1.6	2.5	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS=VDS , ID =2500A		-4.8		mV/°C	
1	Drein Course Lookage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA	
Igss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =7A		32		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.1		Ω	
Qg	Total Gate Charge (4.5V)			9.8			
Qgs	Gate-Source Charge	V <sub>DS</sub> =32V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =7A		2.8		nC	
$Q_{gd}$	Gate-Drain Charge			3.9			
T <sub>d(on)</sub>	Turn-On Delay Time			2.8			
Tr	Rise Time	$V_{DD}$ =20V , $V_{GS}$ =10V , $R_G$ =3.3 $\Omega$		40.4		20	
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =7A		22.8		ns	
T <sub>f</sub>	Fall Time			6.4			
Ciss	Input Capacitance			1013			
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		107		pF	
Crss	Reverse Transfer Capacitance			76			

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			8	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>	VG=VD=UV, FOICe Current			36	А
Vsd	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V
t <sub>rr</sub>	Reverse Recovery Time	IF=7A,dI/dt=100A/µs,		10		nS
Qrr	Reverse Recovery Charge	TJ=25°C		3.3		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

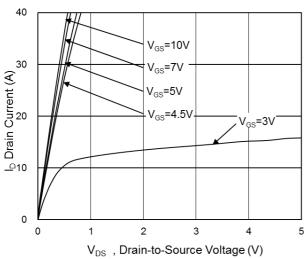
3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =25A

4.The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.







**Fig.1 Typical Output Characteristics** 

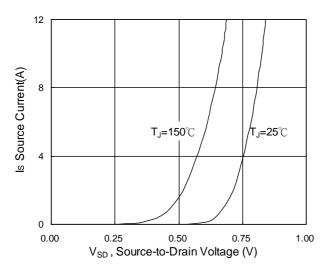


Fig.3 Forward Characteristics of Reverse

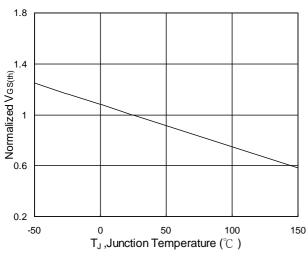


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs.  $T_{\text{J}}$ 

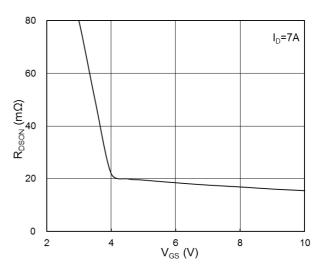


Fig.2 On-Resistance vs. G-S Voltage

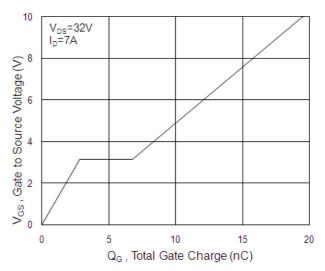


Fig.4 Gate-Charge Characteristics

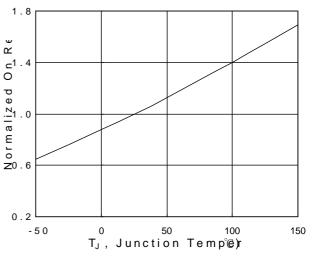
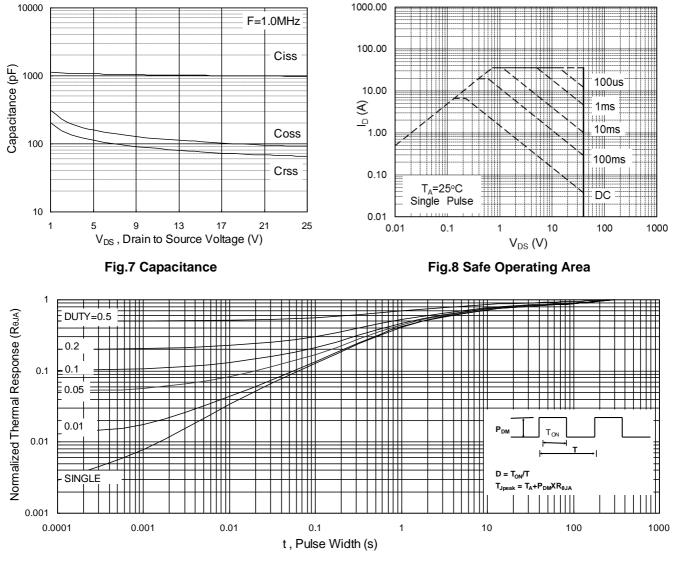


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>







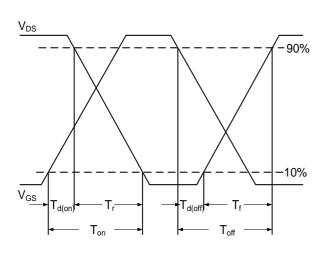


Fig.10 Switching Time Waveform

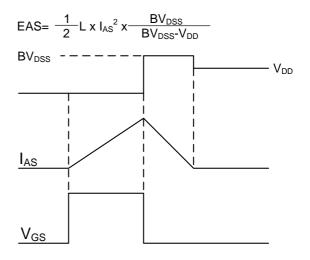
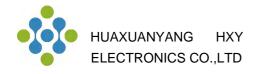
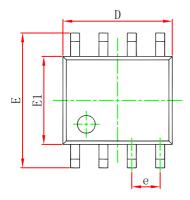
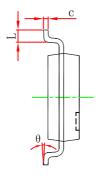


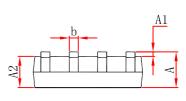
Fig.11 Unclamped Inductive Switching Waveform



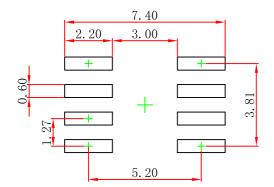
# SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1.270 (BSC)		0.050 (BSC)		
E	5.800	6.200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0 °	8°	0 °	8°	



Note: 1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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